

AMENDMENTS TO THE SPECIFICATION:

Please replace the paragraph beginning on line 18 of page 9 with the following rewritten paragraph:

The capillary forces created by the coating fluid also have the potential to damage the MEMS device. The solvent contained in the coating fluid primarily is responsible for the damage that occurs when the coating is curing. This is because solvents, the primary component of most of the coating fluids of interest, typically have higher a surface tension than the dissolved filler material. For example, common AZ-P3D-SF photoresist contains approximately 85% propylene glycol monomethyl ether (PGMEA) as a solvent. As this solvent evaporates, the capillary forces pull on the mirror and the underlying mechanical structures and can easily bend or break the structures. This damage mechanism, which accounts for much of the damage to micromechanical devices, previously has not been understood. Figure 4 is a cross-section side view of the mirrors shown in Figure 3 after the mirrors have been damaged by the capillary forces of a recoating material. In Figure 4, the mirrors 302 are bent toward the substrate.